

■ Features

- Molding Inductor.
- High reliability.
- High current, low DCR, high efficiency.
- Very low acoustic noise and very low leakage flux noise.
- Operating temperature: $-55^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (Including self-temperature rise) .

■ Applications

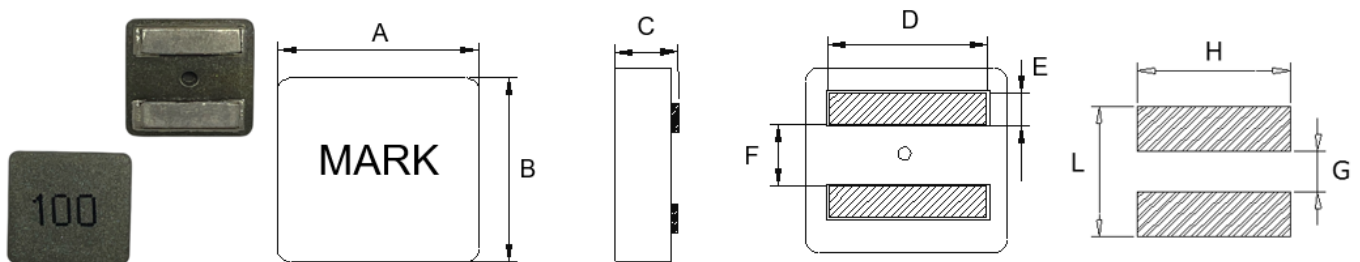
- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.
- DC/DC converter.

■ Product Identification



- (1) : Type
- (2) : Dimensions
- (3) : Inductance value
- (4) : Inductance Tolerance : N= $\pm 30\%$, M= $\pm 20\%$

■ Shapes and Dimensions (Unit: mm)



TYPE	A	B	C	D	E	F	G Ref.	H Ref.	L Ref.
YSPIT1060A	11.9 \pm 0.3	11.0 \pm 0.3	5.7 \pm 0.3	9.2 \pm 0.8	2.4 \pm 0.3	4.4 \pm 0.5	3.7	11.0	10.5

■ YSPIT1060A Series

Part Number	Inductance (uH) @100KHz/0.1V	DCR Max. (mΩ)	Saturation Current (A)		Heat Rating Current Typ.(A)	
			Max.	Typ.	20°C rise	40°C rise
YSPIT1060A-R68M	0.68±20%	1.5	50.0	55.0	22.5	34.0
YSPIT1060A-1R0M	1.0±20%	2.4	44.0	48.0	20.0	28.5
YSPIT1060A-1R2M	1.2±20%	2.7	40.0	45.0	18.0	26.5
YSPIT1060A-1R5M	1.5±20%	3.3	36.0	40.0	16.0	24.5
YSPIT1060A-2R2M	2.2±20%	4.9	30.0	35.0	14.0	20.0
YSPIT1060A-3R3M	3.3±20%	7.7	25.0	28.0	11.4	16.8
YSPIT1060A-4R7M	4.7±20%	10.8	22.0	25.0	8.7	14.0

- ※ The saturation current value is the DC current value having inductance decrease down to 30%.(at 25°C)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40°C. (at 25°C)
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

■ Mechanical Reliability

Item	Specification and Requirement	Test Method
Solderability	1. No case deformation or change in visual 2. New solder coverage More than 95%	1.Preheat : 155°C±5°C , 60S±2S 2.Tin: lead-free. 3.Temperature:240°C±5°C , flux 3.0S±0.5S.
Mechanical shock	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Acceleration : 100G 2. Pulse time: : 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions
Mechanical vibration	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Reflow: 2times 2. Frequency: 10HZ ~ 50HZ ~ 10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm±10% 4. Directions: X,Y,Z 5. Time: 12 cycle / direction

■ Endurance Reliability

Item	Specification and Requirement	Test Method
Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. First -55°C° for 30 minutes, last 125°C° for 30 minutes as 1 cycle. Go through 1000 cycles. 2. Max transfer time is 3 minutes. 3. Measured at room temperature after placing for 24±2 hours
Biased Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1.Reflow 2 times, 2.85°C°±3C°,85%±3%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours
Low temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature : -55 \pm 2C° 2. Time : 1000 hours 3. Measured at room temperature after placing for 24±2 hours
High temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature : +125 \pm 2C° 2. Time : 1000 hours 3. Measured at room temperature after placing for 24±2 hours

Recommended Soldering Technologies

Re-flowing Profile



Preheat condition: 150 ~200°C/60~120sec.
 Allowed time above 217°C: 60~90sec.
 Peak temp: 260°C
 Max time at Peak temp: 10 sec.
 Solder paste: Sn/3.0Ag/0.5Cu
 Allowed Reflow time: 2x max

Iron Soldering Profile



Iron soldering power: Max. 30W
 Pre-heating: 150°C/60sec.
 Soldering Tip temperature: 350°C Max.
 Soldering time: 3sec. Max.
 Solder paste: Sn/3.0Ag/0.5Cu
 Max.1 times for iron soldering

■ Taping Dimensions(Unit:mm)



TYPE	W	P	P0	P2	D0	D1	T	A0	B0	K0	E	F	MPQ
YSPIT1060A	24.0 ±0.3	16.0 ±0.1	4.0 ±0.1	2.0 ±0.1	1.5 ±0.1	1.5 ±0.1	0.35 ±0.05	12.4 ±0.1	11.5 ±0.1	6.3 ±0.1	1.75 ±0.1	11.5 ±0.1	500

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	W2	W3	A	B	C	D
YSPIT1060A	330±2.0	24.4±2.0	30.4MAX	23.9 Min	13.0±0.5	21.0±0.8	2.0±0.5	97±0.5

Direction of rolling



Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.